MOSFET - Power, Single N-Channel, TOLL

NTBLS1D5N08MC 80 V, 1.53 mΩ, 298 A

Features

- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- Lowers Switching Noise/EMI
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	80	V
Gate-to-Source Voltage			V_{GS}	±20	V
Continuous Drain Current R _{θJC} (Note 2)	Steady	$T_C = 25^{\circ}C$	Ι _D	298	Α
Power Dissipation $R_{\theta JC}$ (Note 2)	State	$T_C = 25^{\circ}C$	P _D	250	W
$\begin{array}{c} \text{Continuous Drain} \\ \text{Current R}_{\theta JA} \\ \text{(Notes 1, 2)} \end{array}$	Steady State	T _A = 25°C	I _D	32	Α
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)	State	T _A = 25°C	P _D	2.9	W
Pulsed Drain Current	$T_A = 25$	°C, t _p = 10 μs	I _{DM}	4487	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Source Current (Body Diode)			IS	192	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 31 A, L = 3 mH)			E _{AS}	1441	mJ
Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	0.5	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	43	

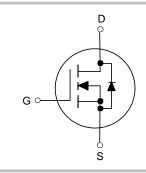
- 1. Surface–mounted on FR4 board using a 1 in² pad size, 1 oz. Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.



ON Semiconductor®

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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
80 V	1.53 mΩ @ 10 V	298 A
	3.7 mΩ @ 6 V	290 A





TOLL CASE 100CU

MARKING DIAGRAM



NTBLS1D5N08MC = Specific Device Code

A = Assembly Location

Y = YearWW = Work WeekZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

Table 1. ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Min	Тур	Max	Units
OFF CHARACTERISTICS	•						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	I _D = 250 μA, V _{GS} = 0 V		80	-	_	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 250 μA, ref to 25°C		-	78	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V	$T_{J} = 25^{\circ}C$ $T_{J} = 125^{\circ}C$	-	-	1 100	μΑ μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V, } V_{G}$		_	_	±100	nA
ON CHARACTERISTICS (Note 3)		30 . 0	<u> </u>	_1			
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_{D}$	= 710 μΑ	2.0	3.0	4.0	V
Negative Threshold Temperature Coefficient	V _{GS(th)} /T _J	$I_D = 710 \mu\text{A}, \text{ ref to } 25^{\circ}\text{C}$		_	-8.3	_	mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 80 A		_	1.30	1.53	mΩ
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 6 \text{ V}, I_{D} = 63 \text{ A}$		_	2.0	3.7	mΩ
Forward Transconductance	9FS	V _{DS} = 5 V, I _E	o = 80 A	-	220	_	S
Gate-Resistance	R_{G}	T _A = 25	i°C	-	0.7	_	Ω
CHARGES & CAPACTIANCES	•			•		•	•
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 40 \text{ V}, f = 1 \text{ MHz}$		_	8170	_	pF
Output Capacitance	C _{oss}			-	3025	_	pF
Reverse Transfer Capacitance	C _{rss}			-	82	_	pF
Total Gate Charge	Q _{G(tot)}	$V_{GS} = 10 \text{ V}, V_{DS} = 40 \text{ V},$ $I_{D} = 80 \text{ A}$		-	111	_	nC
Threshold Gate Charge	Q _{G(th)}			-	22	_	
Gate-to-Source Charge	Q_{gs}			_	35	_	
Gate-to-Drain Charge	Q_{gd}			_	23	_	
Output Charge	Q _{oss}			-	166	_	
Sync Charge	Q _{sync}			-	94	_	
Plateau Voltage	V_{P}			-	5	_	V
SWITCHING CHARACTERISTICS, $V_{GS} = 10$	V (Note 3)						
Turn-On Delay Time	t _{d(on)}	$V_{GS} = 10 \text{ V}, V_{DS} = 40 \text{ V},$ $I_{D} = 80 \text{ A}, R_{G} = 6 \Omega$		_	38	_	ns
Rise Time	t _r			-	34	_	ns
Turn-Off Delay Time	t _{d(off)}			-	74	_	ns
Fall Time	t _f			-	37	_	ns
DRAIN-SOURCE DIODE CHARACTERISTI	cs						
Forward Diode Voltage		I _S = 80 A, V _{GS} = 0 V	$T_J = 25^{\circ}C$	-	0.8	1.3	V
		I _S = 80 A, V _{GS} = 0 V	T _J = 125°C	-	0.7	_	V
Reverse Recovery Time	t _{rr}	I _F = 40 A, di/dt = 300 A/μs		-	19	_	nS
Reverse Recovery Charge	Q _{rr}			-	42	_	nC
Reverse Recovery Time	t _{rr}	I _F = 40 A, di/dt = 1000 A/μs		-	17	_	nS
Reverse Recovery Charge	Q _{rr}			_	121	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures

TYPICAL CHARACTERISTICS

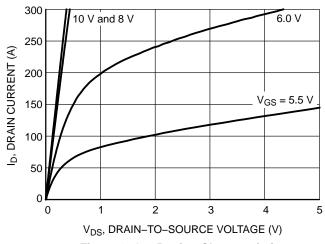


Figure 1. On-Region Characteristics

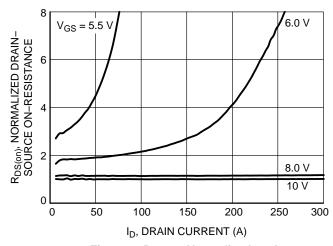


Figure 2. R_{DS(on)} Normalized vs. I_D

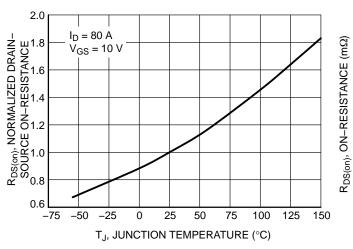


Figure 3. R_{DS(on)} vs. Junction Temperature

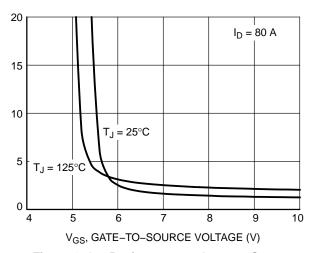


Figure 4. On-Resistance vs. Gate-to-Source Voltage

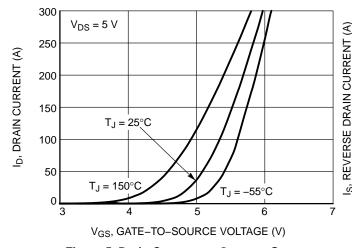


Figure 5. Drain Current vs. Gate-to-Source Voltage

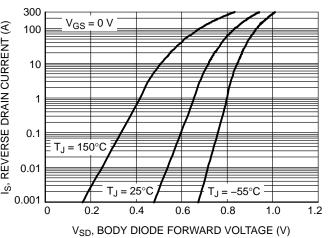
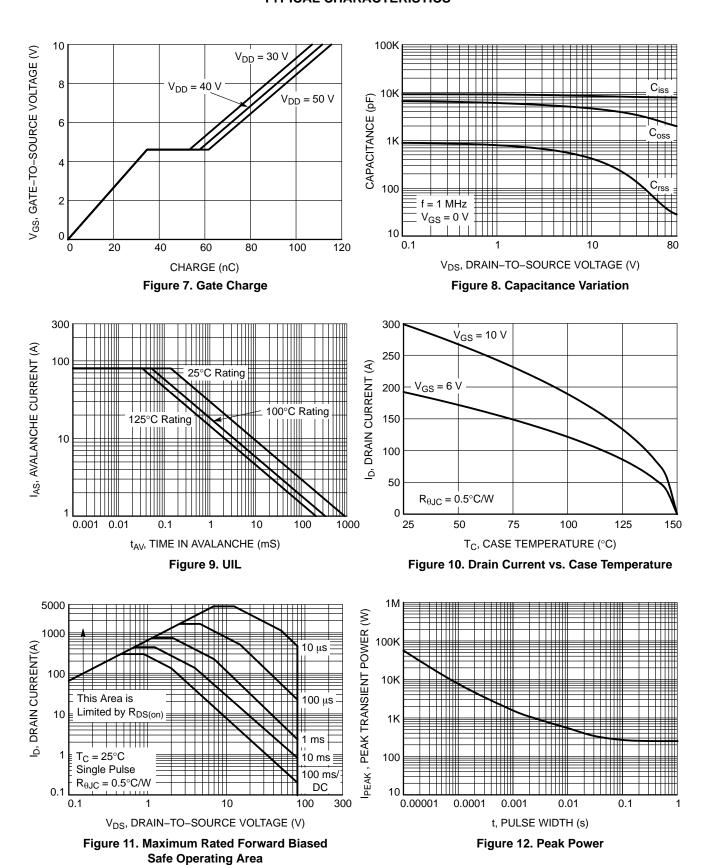


Figure 6. Reverse Drain Current vs. Body Diode Forward Voltage

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

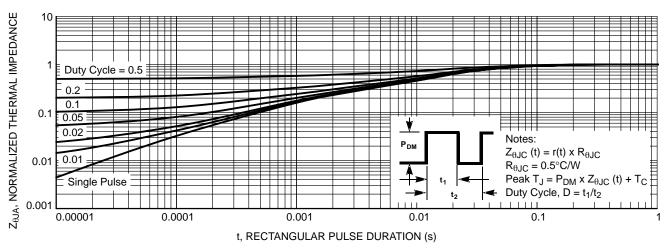


Figure 13. Transient Thermal Impedance

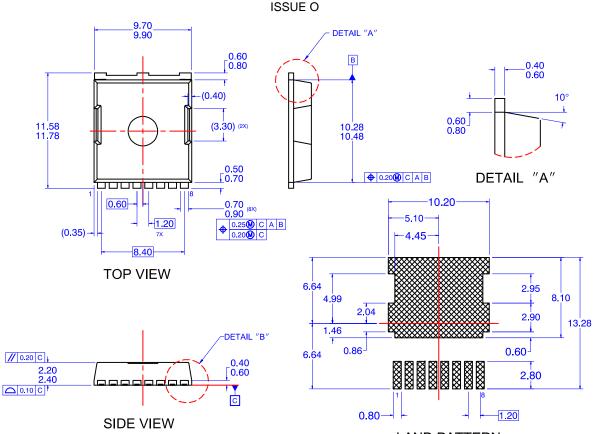
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTBLS1D5N08MC	NTBLS 1D5N08MC	M0-299A (Pb-Free)	2000 / Tape & Reel

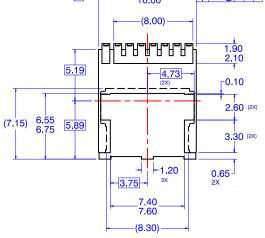
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

H-PSOF8L 11.68x9.80 CASE 100CU

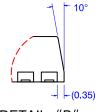


9,80 10.00 (8,00)



BOTTOM VIEW

LAND PATTERN RECOMMENDATION



DETAIL "B"

NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER 2009.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

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